

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hikomichi ISOGAI</td> <td>10/29/2009</td> </tr> <tr> <td>Takeshi SENDA</td> <td>10/29/2009</td> </tr> <tr> <td>Eiji TOYODA</td> <td>10/29/2009</td> </tr> <tr> <td>Kumiko MURAYAMA</td> <td>10/29/2009</td> </tr> <tr> <td>Koji IZUNOME</td> <td>10/29/2009</td> </tr> <tr> <td>Susumu MAEDA</td> <td>10/29/2009</td> </tr> <tr> <td>Kazuhiko KASHIMA</td> <td>10/29/2009</td> </tr> </tbody> </table>		Name	Execution Date	Hikomichi ISOGAI	10/29/2009	Takeshi SENDA	10/29/2009	Eiji TOYODA	10/29/2009	Kumiko MURAYAMA	10/29/2009	Koji IZUNOME	10/29/2009	Susumu MAEDA	10/29/2009	Kazuhiko KASHIMA	10/29/2009
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RECEIVING PARTY DATA																	
Name:	COVALENT MATERIALS CORPORATION																
Street Address:	6-3, Ohsaki 1-chome, Shinagawa-ku																
City:	Tokyo																
State/Country:	JAPAN																
Postal Code:	141-0032																
PROPERTY NUMBERS Total: 1																	
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12512229</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12512229												
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CORRESPONDENCE DATA																	
Fax Number:	(202)672-5399																
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OP \$40.00 12512229

501013299

PATENT
REEL: 023506 FRAME: 0280

NAME OF SUBMITTER:

Pavan K. Agarwal

Total Attachments: 2

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ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, each undersigned inventor has sold and assigned, and by these presents hereby sells and assigns, unto

name and address of assignee

COVALENT MATERIALS CORPORATION
6-3, Ohsaki 1-chome, Shinagawa-ku, Tokyo 141-0032 Japan

(hereinafter ASSIGNEE) all right, title and interest for the United States, its territories and possessions in and to this invention relating to

title of invention

MANUFACTURING METHOD FOR SILICON WAFER

as set forth in this United States Patent Application

check one

- executed concurrently herewith
- executed on _____
- Serial No. 12/512,229 Filed July 30, 2009

in and to said United States Patent Application including any and all divisions or continuations thereof and in and to any and all Letters Patent of the United States which may issue on any such application or for said invention, including any and all reissues or extensions thereof, to be held and enjoyed by said ASSIGNEE, its successors, legal representatives and assigns to the full end of the term or terms for which any and all such Letters Patent may be granted as fully and entirely as would have been held and enjoyed by the undersigned had this Assignment not been made;

Each of the undersigned hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all such Letters Patent to said ASSIGNEE, its successors or assigns in accordance herewith;

Each of the undersigned warrants and covenants that he has the full and unencumbered right to sell and assign the interests herein sold and assigned and that he has not executed and will not execute any document or instrument in conflict herewith;

Each of the undersigned further covenants and agrees he will communicate to said ASSIGNEE, its successors, legal representatives or assigns all information known to him relating to said invention or patent application and that he will execute and deliver any papers, make all rightful oaths, testify in any legal proceedings and perform all other lawful acts deemed necessary or desirable by said ASSIGNEE, its successors, legal representatives or assigns to perfect title to said invention, to said application including divisions and continuations thereof and to any and all Letters Patent which may be granted therefor or thereon, including reissues or extensions, in said ASSIGNEE, its successors, or assigns or to assist said ASSIGNEE, its successors, legal representatives or assigns in obtaining, reissuing or enforcing Letters Patent of the United States for said invention;

Each of the undersigned hereby grants the firm of FOLEY & LARDNER the power to insert in this Assignment any further identification which may be necessary or desirable to comply with the rules of the U.S. Patent and Trademark Office for recordation of this Assignment.

NAMES AND SIGNATURES OF INVENTORS		
Name: Hironichi ISOGAI	Signature: <i>Hironichi Isogai</i>	Date: 10/29/2009
Name: Takeshi SENDA	Signature: <i>Takeshi Senda</i>	Date: 10/29/2009
Name: Eiji TOYODA	Signature: <i>Eiji Toyoda</i>	Date: 10/29/2009
Name: Kumiko MURAYAMA	Signature: <i>Kumiko Murayama</i>	Date: 10/29/2009
NAMES AND SIGNATURES OF WITNESSES		
Name:	Signature:	Date:
Name:	Signature:	Date:

Note: *Prima facie* evidence of execution may optionally be obtained by execution of this document before a U.S. Consul or before a local officer authorized to administer oaths whose authority is proved by a certificate from the U.S. Consul.

PATENT

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Name: Koji IZUNOME	Signature: <i>Koji Izunome</i>	Date: 10/29/2009
Name: Susumu MAEDA	Signature: <i>Susumu Maeda</i>	Date: 10/29/2009
Name: Kazuhiko KASHIMA	Signature: <i>Kazuhiko Kashima</i>	Date: 10/29/2009
Name:	Signature:	Date:
NAMES AND SIGNATURES OF WITNESSES		
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RECORDED: 11/12/2009

REEL: 023506 FRAME: 0283